

BARLOW, JOSEPHS & HOLMES, LTD.  
101 DYER STREET, SUITE 501  
PROVIDENCE, RI 02903  
TELEPHONE: 401-273-4446  
FACSIMILE: 401-273-4447

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ABSTRACT OF DISCLOSURE

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15. The method of Claim 11, wherein said first thermally conductive filler has particles that are substantially strand-shaped.

[c16]

16. The method of Claim 11, wherein said first thermally conductive filler has particles that are substantially whisker-shaped.

[c17]

17. The method of Claim 11, wherein said first thermally conductive filler is a material selected from the group consisting of aluminum, alumina, copper, magnesium, brass and carbon.

[c18]

18. The method of Claim 11, wherein said second thermally conductive filler material is boron nitride grains.

[c19]

19. The method of Claim 11, wherein said second thermally conductive filler has particles that are substantially grain shaped.

[c20]

20. The method of Claim 11, wherein said second thermally conductive filler is a material selected from the group consisting of aluminum, alumina, copper, magnesium, brass, boron nitride and carbon.

## Abstract of Disclosure

[0044] The present invention discloses a conductive injection molding composition. The thermally conductive composition includes a metallic base matrix of, by volume, between 30 and 60 percent. A first thermally conductive filler, by volume, between 25 and 60 percent is provided in the composition that has a relatively high aspect ratio of at least 10:1. In addition, an alternative embodiment of the composition mixture includes a second thermally conductive filler, by volume, between 10 and 25 percent that has a relatively low aspect ratio of 5:1 or less.

## Figures